## DATA SHEET



# BYX10G <br> Rectifier 

Product specification

## FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Available in ammo-pack.


## DESCRIPTION

Rugged glass package, using a high temperature alloyed construction.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.

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Fig. 1 Simplified outline (SOD57) and symbol.

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $V_{\text {RSM }}$ | non-repetitive peak reverse voltage |  | - | 1600 | V |
| $V_{\text {RRM }}$ | repetitive peak reverse voltage |  | - | 1600 | V |
| $\mathrm{V}_{\text {RWM }}$ | crest working reverse voltage |  | - | 800 | V |
| $\mathrm{I}_{\text {F (AV) }}$ | average forward current | $\mathrm{T}_{\mathrm{tp}}=50^{\circ} \mathrm{C} ;$ <br> lead length = 10 mm ; averaged over any 20 ms period; see Figs 2 and 4 | - | 1.2 | A |
|  |  | $\mathrm{T}_{\text {amb }}=60^{\circ} \mathrm{C}$; PCB mounting (see Fig.9); averaged over any 20 ms period; see Figs 3 and 4 | - | 0.6 | A |
| $\mathrm{I}_{\text {FSM }}$ | non-repetitive peak forward current | $\begin{aligned} & t=10 \mathrm{~ms} \text { half sinewave; } \\ & T_{j}=T_{j \text { max }} \text { prior to surge; } \\ & \mathrm{V}_{\mathrm{R}}=\mathrm{V}_{\mathrm{RWM} \text { max }} \end{aligned}$ | - | 25 | A |
| $\mathrm{T}_{\text {stg }}$ | storage temperature |  | -65 | +175 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{j}}$ | junction temperature | see Fig. 5 | -65 | +175 | ${ }^{\circ} \mathrm{C}$ |

## ELECTRICAL CHARACTERISTICS

$\mathrm{T}_{\mathrm{j}}=25^{\circ} \mathrm{C}$; unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{F}}$ | forward voltage | $\mathrm{I}_{\mathrm{F}}=2 \mathrm{~A} ; \mathrm{T}_{\mathrm{j}}=\mathrm{T}_{\mathrm{j} \text { max; }}$ see Fig. 6 | - | - | 1.5 | V |
|  |  | $\mathrm{I}_{\mathrm{F}}=2 \mathrm{~A}$; see Fig. 6 | - | - | 1.5 | V |
| $\mathrm{I}_{\mathrm{R}}$ | reverse current | $\mathrm{V}_{\mathrm{R}}=\mathrm{V}_{\text {RWMmax }}$; see Fig. 7 | - | - | 1 | $\mu \mathrm{A}$ |
|  |  | $\mathrm{V}_{R}=\mathrm{V}_{\text {RWMmax }} ; \mathrm{T}_{\mathrm{j}}=150{ }^{\circ} \mathrm{C}$; see Fig. 7 | - | - | 200 | $\mu \mathrm{A}$ |
| $\mathrm{t}_{\mathrm{rr}}$ | reverse recovery time | when switched from $I_{F}=0.5$ A to $I_{R}=1 \mathrm{~A}$; measured at $\mathrm{I}_{\mathrm{R}}=0.25 \mathrm{~A}$; see Fig. 10 | - | 3 | - | $\mu \mathrm{s}$ |
| $\mathrm{C}_{\mathrm{d}}$ | diode capacitance | $\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V} ; \mathrm{f}=1 \mathrm{MHz}$; see Fig. 8 | - | 30 | - | pF |

THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
| :--- | :--- | :--- | ---: | :---: |
| $\mathrm{R}_{\text {th j }-\mathrm{tp}}$ | thermal resistance from junction to tie-point | lead length $=10 \mathrm{~mm}$ | 46 | K/W |
| $\mathrm{R}_{\mathrm{th} \text { j }-\mathrm{a}}$ | thermal resistance from junction to ambient | note 1 | 100 | K/W |

## Note

1. Device mounted on epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper $\geq 40 \mu \mathrm{~m}$, see Fig. 9 . For more information please refer to the "General Part of associated Handbook".

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## GRAPHICAL DATA


$\mathrm{a}=1.57 ; \mathrm{V}_{\mathrm{R}}=\mathrm{V}_{\mathrm{RWM} \max } ; \delta=0.5$.
Lead length 10 mm .
Fig. 2 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).

$\mathrm{a}=\mathrm{I}_{\mathrm{F}(\mathrm{RMS})} / \mathrm{I}_{\mathrm{F}(\mathrm{AV})} ; \mathrm{V}_{\mathrm{R}}=\mathrm{V}_{\mathrm{RWM} \max } ; \delta=0.5$.
Fig. 4 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.

$\mathrm{a}=1.57 ; \mathrm{V}_{\mathrm{R}}=\mathrm{V}_{\mathrm{RWM} \max } ; \delta=0.5$.
Device mounted as shown in Fig.9.
Fig. 3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).


## Solid line $=\mathrm{V}_{\mathrm{R}}$.

Dotted line $=\mathrm{V}_{\mathrm{RWM}} ; \delta=0.5$.
Fig. 5 Maximum permissible junction temperature as a function of reverse voltage.

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Fig. 6 Forward current as a function of forward voltage; maximum values.

$\mathrm{f}=1 \mathrm{MHz} ; \mathrm{T}_{\mathrm{j}}=25^{\circ} \mathrm{C}$.
Fig. 8 Diode capacitance as a function of reverse voltage; typical values.


Fig. 7 Reverse current as a function of junction temperature; maximum values.


Fig. 9 Device mounted on a printed-circuit board.



Input impedance oscilloscope: $1 \mathrm{M} \Omega$, $22 \mathrm{pF} ; \mathrm{t}_{\mathrm{r}} \leq 7 \mathrm{~ns}$.
Source impedance: $50 \Omega$; $\mathrm{t}_{\mathrm{r}} \leq 15 \mathrm{~ns}$.
Fig. 10 Test circuit and reverse recovery time waveform and definition.

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## PACKAGE OUTLINE

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## DEFINITIONS

| Data sheet status |  |
| :--- | :--- |
| Objective specification | This data sheet contains target or goal specifications for product development. |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification | This data sheet contains final product specifications. |
| Limiting values | Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or <br> more of the e limiting values may cause permanent damage to the device. These are stress ratings only and operation <br> of the device at these or an any other conditions above those given in the Characteristics sections of the specification <br> is not implied. Exposure to limiting values for extended periods may affect device reliability. |
| Application information |  |
| Where application information is given, it is advisory and does not form part of the specification. |  |

## LIFE SUPPORT APPLICATIONS

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